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RL78/L13

R01DS0168EJ0210

RENESAS MCU

Rev.2.10

Aug 12, 2016

Integrated LCD controller/driver, True Low Power Platform (as low as 112.5 μ A/MHz, and 0.61 μ A for RTC + LVD), 1.6 V to 5.5 V operation, 16 to 128 Kbyte Flash, 31 DMIPS at 24 MHz, for All LCD Based Applications

1. OUTLINE

<R> 1.1 Features

Ultra-low power consumption technology

- V_{DD} = single power supply voltage of 1.6 to 5.5 V which can operate a 1.8 V device at a low voltage
- HALT mode
- STOP mode
- SNOOZE mode

RL78 CPU core

- CISC architecture with 3-stage pipeline
- Minimum instruction execution time: Can be changed from high speed (0.04167 μ s: @ 24 MHz operation with high-speed on-chip oscillator) to ultra-low speed (30.5 μ s: @ 32.768 kHz operation with subsystem clock)
- Address space: 1 MB
- General-purpose registers: (8-bit register \times 8) \times 4 banks
- On-chip RAM: 1 to 8 KB

Code flash memory

- Code flash memory: 16 to 128 KB
- Block size: 1 KB
- Prohibition of block erase and rewriting (security function)
- On-chip debug function
- Self-programming (with boot swap function/flash shield window function)

Data flash memory

- Data flash memory: 4 KB
- Back ground operation (BGO): Instructions can be executed from the program memory while rewriting the data flash memory.
- Number of rewrites: 1,000,000 times (TYP.)
- Voltage of rewrites: V_{DD} = 1.8 to 5.5 V

High-speed on-chip oscillator

- Select from 48 MHz, 24 MHz, 16 MHz, 12 MHz, 8 MHz, 6 MHz, 4 MHz, 3 MHz, 2 MHz, and 1 MHz
- High accuracy: \pm 1.0 % (V_{DD} = 1.8 to 5.5 V, T_A = -20 to +85°C)

Operating ambient temperature

- T_A = -40 to +85°C (A: Consumer applications)
- T_A = -40 to +105°C (G: Industrial applications)

Power management and reset function

- On-chip power-on-reset (POR) circuit
- On-chip voltage detector (LVD) (Select interrupt and reset from 14 levels)

DMA (Direct Memory Access) controller

- 4 channels
- Number of clocks during transfer between 8/16-bit SFR and internal RAM: 2 clocks

Multiplier and divider/multiplier-accumulator

- 16 bits \times 16 bits = 32 bits (Unsigned or signed)
- 32 bits \div 32 bits = 32 bits (Unsigned)
- 16 bits \times 16 bits + 32 bits = 32 bits (Unsigned or signed)

Serial interface

- CSI: 2 channels
- UART/UART (LIN-bus supported): 3, 4 channels/1 channel
- I²C/Simplified I²C communication: 1 channel/2 channels

Timer

- 16-bit timer: 8 channels (with remote control output function)
- 16-bit timer KB20 (IH): 1 channel (IH-only PWM output function)
- 12-bit interval timer: 1 channel
- Real-time clock 2: 1 channel (calendar for 99 years, alarm function, and clock correction function)
- Watchdog timer: 1 channel (operable with the dedicated low-speed on-chip oscillator)

A/D converter

- 8/10-bit resolution A/D converter (V_{DD} = 1.6 to 5.5 V)
- Analog input: 9 to 12 channels
- Internal reference voltage (1.45 V) and temperature sensor^{Note 1}

Comparator

- 2 channels
- Operation mode: Comparator high-speed mode, comparator low-speed mode, or window mode
- External reference voltage and internal reference voltage are selectable

LCD controller/driver

- Segment signal output: 36 (32)^{Note 2} to 51 (47)^{Note 2}
- Common signal output: 4 (8)^{Note 2}
- Internal voltage boosting method, capacitor split method, and external resistance division method are switchable

I/O port

- I/O port: 49 to 65 (N-ch open drain I/O [withstand voltage of 6 V]: 2, N-ch open drain I/O [V_{DD} withstand voltage]: 12 to 18)
- Can be set to N-ch open drain, TTL input buffer, and on-chip pull-up resistor
- Different potential interface: Can connect to a 1.8/2.5/3 V device
- On-chip key interrupt function
- On-chip clock output/buzzer output controller

Others

- On-chip BCD (binary-coded decimal) correction circuit

Notes 1. Can be selected only in HS (high-speed main) mode
2. The values in parentheses are the number of signal outputs when 8 com is used.

Remark The functions mounted depend on the product. See 1.6 Outline of Functions.

* There are differences in specifications between every product.
Please refer to specification for details.

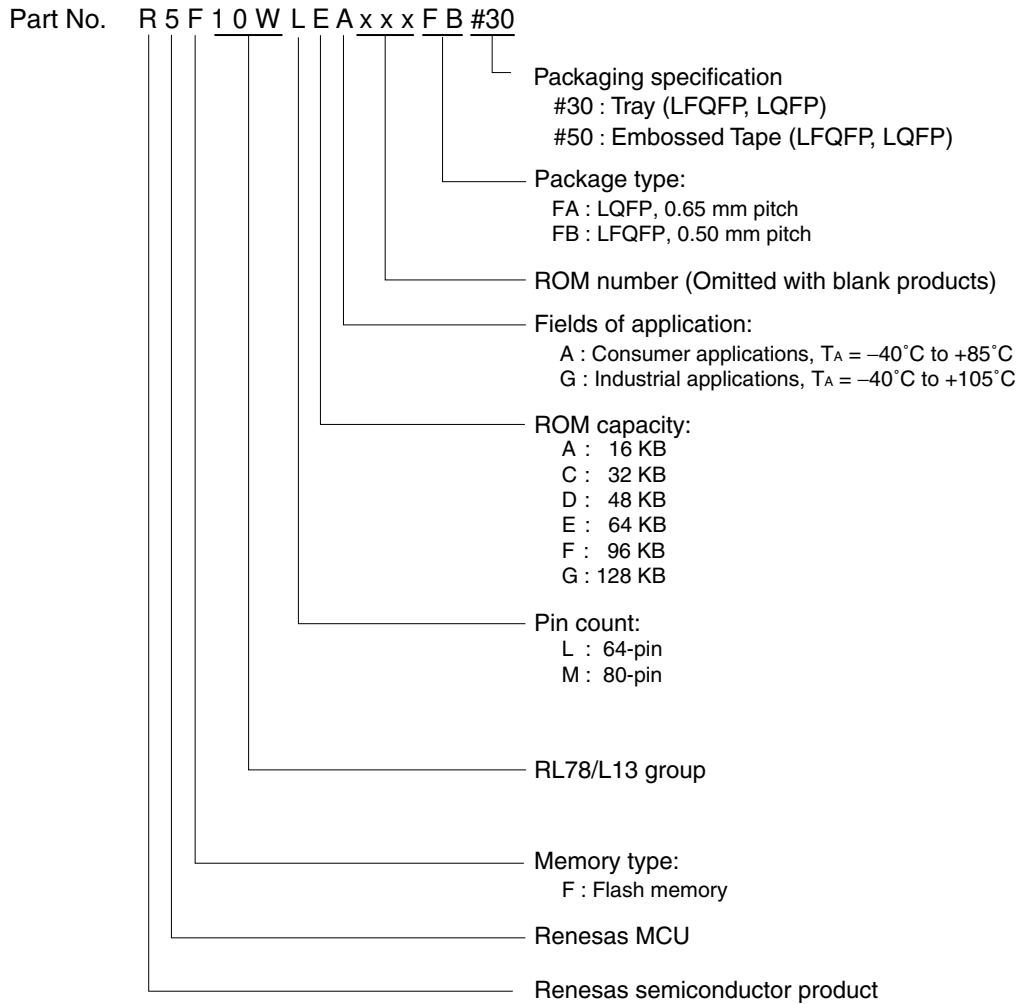
○ ROM, RAM capacities

Flash ROM	Data Flash	RAM	RL78/L13	
			64 pins	80 pins
128 KB	4 KB	8 KB ^{Note}	R5F10WLG	R5F10WMG
96 KB	4 KB	6 KB	R5F10WLF	R5F10WMF
64 KB	4 KB	4 KB	R5F10WLE	R5F10WME
48 KB	4 KB	2 KB	R5F10WLD	R5F10WMD
32 KB	4 KB	1.5 KB	R5F10WLC	R5F10WMC
16 KB	4 KB	1 KB	R5F10WLA	R5F10WMA

Note This is about 7 KB when the self-programming function and data flash function are used. (For details, see **CHAPTER 3** in the RL78/L13 User's Manual.)

1.2 List of Part Numbers

Figure 1-1. Part Number, Memory Size, and Package of RL78/L13



Pin Count	Package	Data Flash	Fields of Application ^{Note}	Ordering Part Number
64 pins	64-pin plastic LQFP (12 × 12 mm, 0.65 mm pitch)	Mounted	A	R5F10WLAFA#30, R5F10WLAFA#50, R5F10WLCAFA#30, R5F10WLCAFA#50, R5F10WLDAFA#30, R5F10WLDAFA#50, R5F10WLEAFA#30, R5F10WLEAFA#50, R5F10WLFAFA#30, R5F10WLFAFA#50, R5F10WLGAF#30, R5F10WLGAF#50
	64-pin plastic LFQFP (10 × 10 mm, 0.5 mm pitch)	Mounted	A G	R5F10WLAFA#30, R5F10WLAFA#50, R5F10WLCAFA#30, R5F10WLCAFA#50, R5F10WLDAFA#30, R5F10WLDAFA#50, R5F10WLEAFA#30, R5F10WLEAFA#50, R5F10WLFAFA#30, R5F10WLFAFA#50, R5F10WLAGAF#30, R5F10WLAGAF#50, R5F10WLCGAF#30, R5F10WLCGAF#50, R5F10WLDGAF#30, R5F10WLDGAF#50, R5F10WLEGF#30, R5F10WLEGF#50, R5F10WLFGAF#30, R5F10WLFGAF#50, R5F10WLGAF#30, R5F10WLGAF#50
80 pins	80-pin plastic LQFP (14 × 14 mm, 0.65 mm pitch)	Mounted	A	R5F10WMAFA#30, R5F10WMAFA#50, R5F10WMCFA#30, R5F10WMCFA#50, R5F10WMDAFA#30, R5F10WMDAFA#50, R5F10WMEAFA#30, R5F10WMEAFA#50, R5F10WMFAFA#30, R5F10WMFAFA#50, R5F10WMGAFA#30, R5F10WMGAFA#50
	80-pin plastic LFQFP (12 × 12 mm, 0.5 mm pitch)	Mounted	A G	R5F10WMAFA#30, R5F10WMAFA#50, R5F10WMCFA#30, R5F10WMCFA#50, R5F10WMDAFA#30, R5F10WMDAFA#50, R5F10WMEAFA#30, R5F10WMEAFA#50, R5F10WMFAFA#30, R5F10WMFAFA#50, R5F10WMGAFA#30, R5F10WMGAFA#50, R5F10WMAGAF#30, R5F10WMAGAF#50, R5F10WMCAGAF#30, R5F10WMCAGAF#50, R5F10WMDAGAF#30, R5F10WMDAGAF#50, R5F10WMEGAF#30, R5F10WMEGAF#50, R5F10WMFGAF#30, R5F10WMFGAF#50, R5F10WMGAF#30, R5F10WMGAF#50

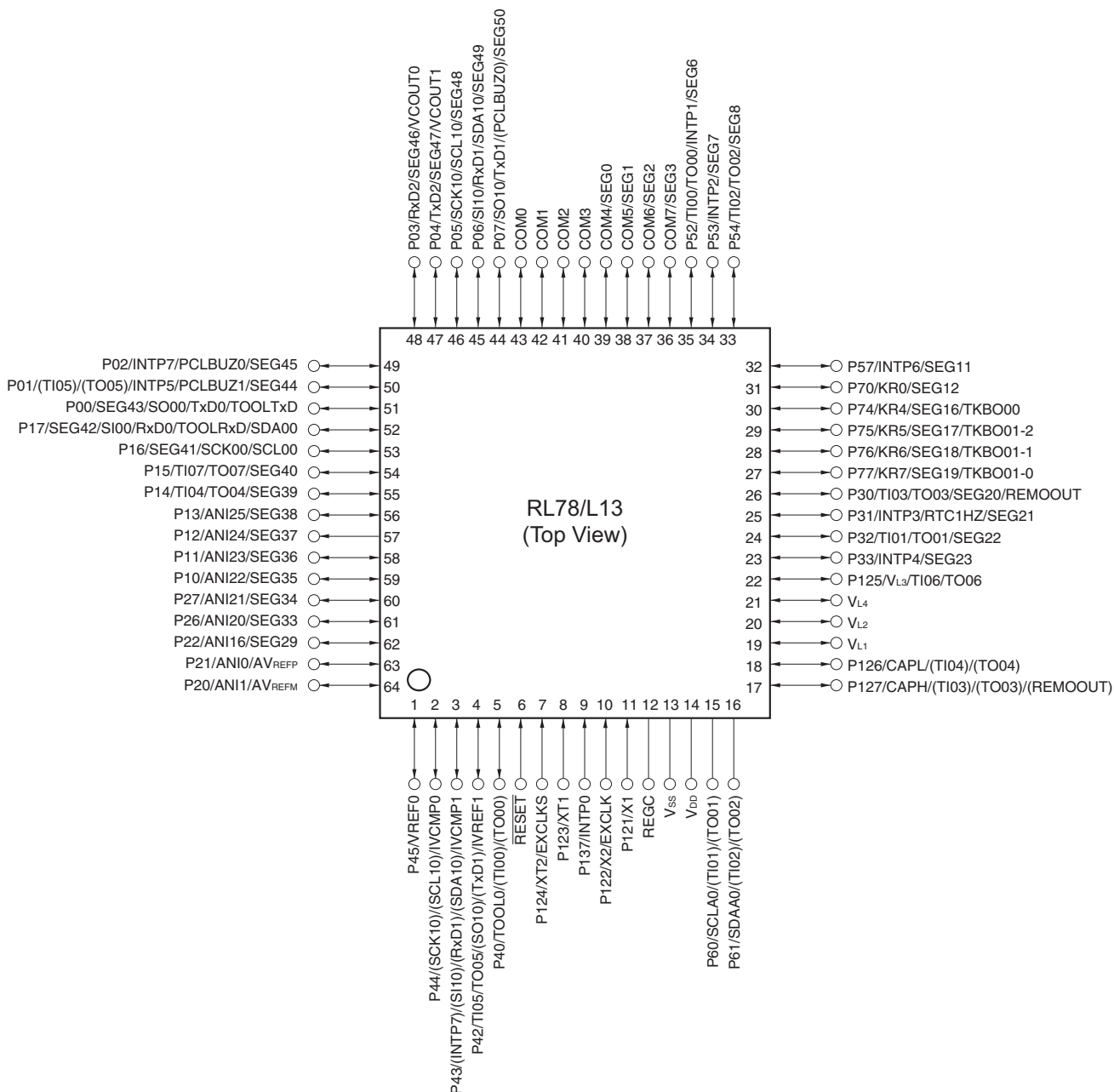
Note For the fields of application, see **Figure 1-1 Part Number, Memory Size, and Package of RL78/L13**.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

1.3 Pin Configuration (Top View)

<R> 1.3.1 64-pin products

- 64-pin plastic LQFP (12 × 12 mm, 0.65 mm pitch)
- 64-pin plastic LFQFP (10 × 10 mm, 0.5 mm pitch)



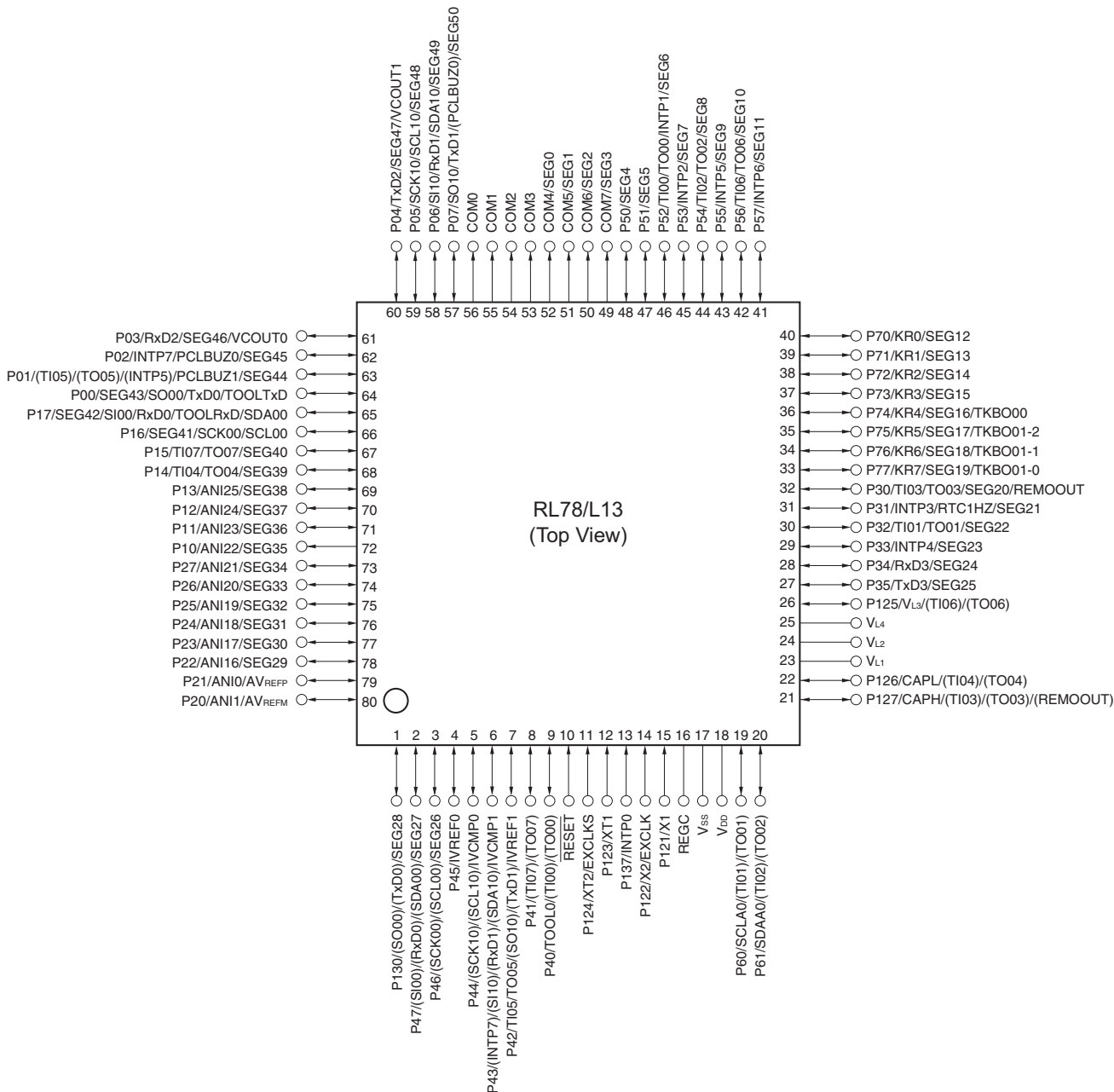
Caution Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μF).

Remarks 1. For pin identification, see 1.4 Pin Identification.

2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). See **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/L13 User’s Manual.

<R> 1.3.2 80-pin products

- 80-pin plastic LQFP (14 × 14 mm, 0.65 mm pitch)
- 80-pin plastic LFQFP (12 × 12 mm, 0.5 mm pitch)



Caution Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μF).

Remarks 1. For pin identification, see 1.4 Pin Identification.

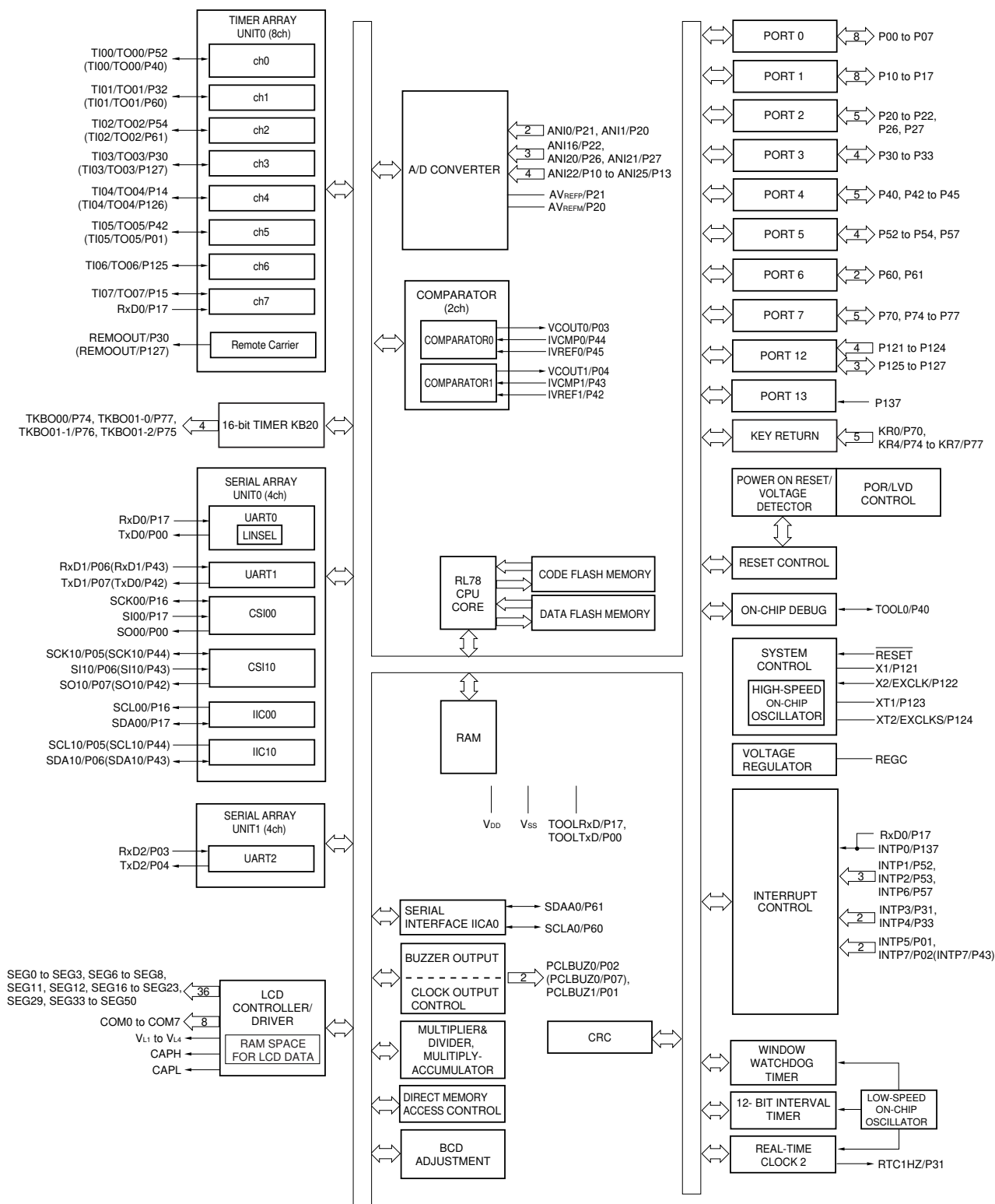
2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). See **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/L13 User's Manual.

1.4 Pin Identification

ANI0, ANI1, ANI16 to ANI25:	Analog Input	PCLBUZ0, PCLBUZ1:	Programmable Clock Output/ Buzzer Output
AVREFM:	Analog Reference Voltage Minus	REGC:	Regulator Capacitance
AVREFP:	Analog Reference Voltage Plus	REMOOUT:	Remote control Output
CAPH, CAPL:	Capacitor for LCD	$\overline{\text{RESET}}$:	Reset
COM0 to COM7:	LCD Common Output	RTC1HZ:	Real-time Clock 2 Correction Clock (1 Hz) Output
EXCLK:	External Clock Input (Main System Clock)	RxD0 to RxD3:	Receive Data
EXCLKS:	External Clock Input (Subsystem Clock)	SCK00, SCK10, SCLA0:	Serial Clock Input/Output
INTP0 to INTP7:	External Interrupt Input	SCL00, SCL10:	Serial Clock Output
IVCMP0, IVCMP1:	Comparator Input	SDAA0, SDA00, SDA10:	Serial Data Input/Output
IVREF0, IVREF1:	Comparator Reference Input	SEG0 to SEG50:	LCD Segment Output
KR0 to KR7:	Key Return	SI00, SI10:	Serial Data Input
P00 to P07:	Port 0	SO00, SO10:	Serial Data Output
P10 to P17:	Port 1	TI00 to TI07:	Timer Input
P20 to P27:	Port 2	TO00 to TO07, TKBO00, TKBO01-0, TKBO01-1, TKBO01-2:	Timer Output
P30 to P35:	Port 3	TOOL0:	Data Input/Output for Tool
P40 to P47:	Port 4	TOOLRxD, TOOLTxD:	Data Input/Output for External Device
P50 to P57:	Port 5	TxD0 to TxD3:	Transmit Data
P60, P61:	Port 6	VCOUT0, VCOUT1:	Comparator Output
P70 to P77:	Port 7	V _{DD} :	Power Supply
P121 to P127:	Port 12	V _{L1} to V _{L4} :	LCD Power Supply
P130, P137:	Port 13	V _{SS} :	Ground
		X1, X2:	Crystal Oscillator (Main System Clock)
		XT1, XT2:	Crystal Oscillator (Subsystem Clock)

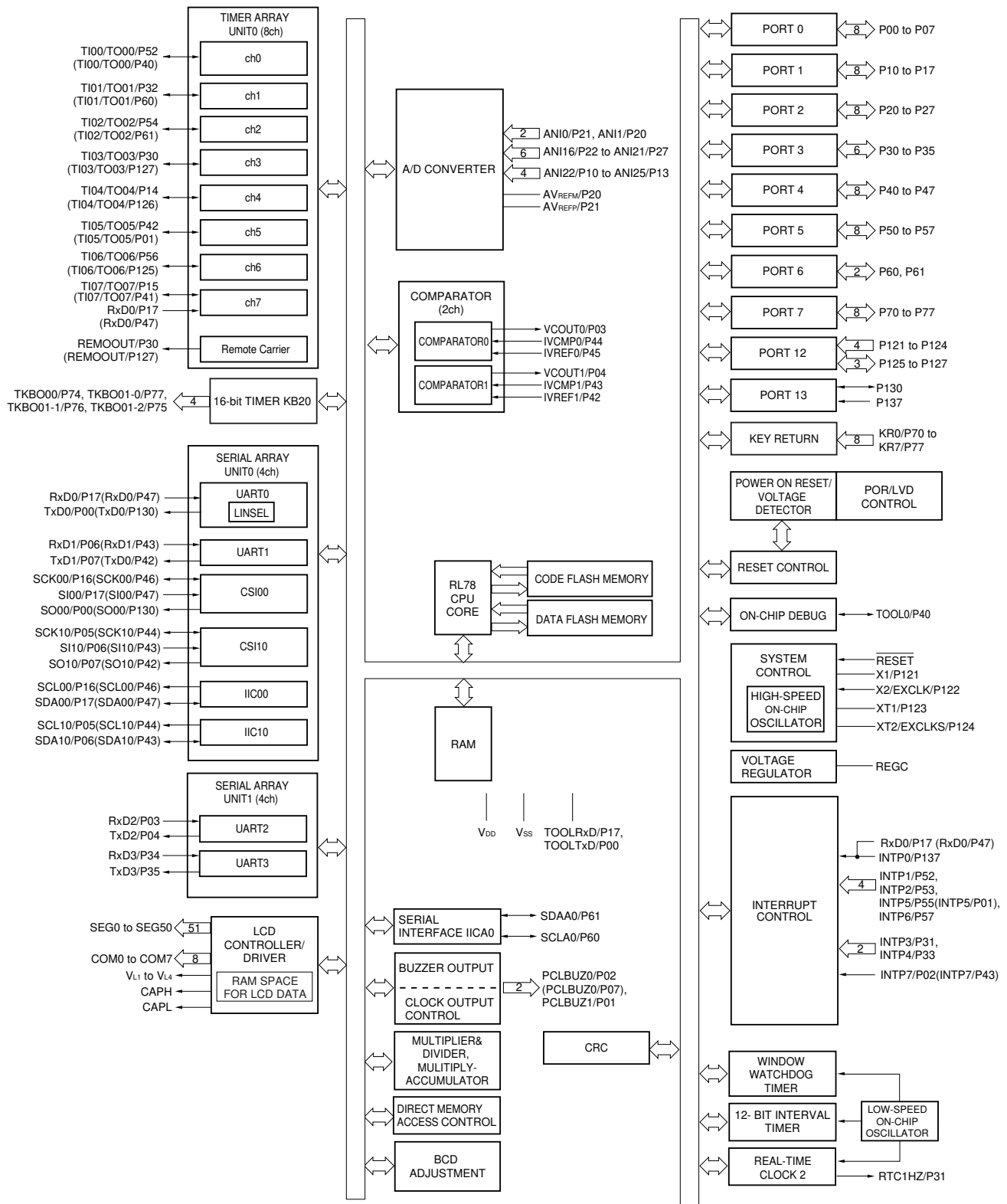
1.5 Block Diagram

1.5.1 64-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). See **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/L13 User's Manual.

1.5.2 80-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). See **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/L13 User's Manual.

1.6 Outline of Functions

(1/2)

Item		64-pin	80-pin
		R5F10WLx (x = A, C-G)	R5F10WMx (x = A, C-G)
Code flash memory (KB)		16 to 128	16 to 128
Data flash memory (KB)		4	4
RAM (KB)		1 to 8 ^{Note 1}	1 to 8 ^{Note 1}
Address space		1 MB	
<R>	Main system clock	X1 (crystal/ceramic) oscillation, external main system clock input (EXCLK) HS (High-speed main) mode: 1 to 20 MHz (V _{DD} = 2.7 to 5.5 V), HS (High-speed main) mode: 1 to 16 MHz (V _{DD} = 2.4 to 5.5 V), LS (Low-speed main) mode: 1 to 8 MHz (V _{DD} = 1.8 to 5.5 V), LV (Low-voltage main) mode: 1 to 4 MHz (V _{DD} = 1.6 to 5.5 V)	
	High-speed on-chip oscillator	HS (High-speed main) mode: 1 to 24 MHz (V _{DD} = 2.7 to 5.5 V), HS (High-speed main) mode: 1 to 16 MHz (V _{DD} = 2.4 to 5.5 V), LS (Low-speed main) mode: 1 to 8 MHz (V _{DD} = 1.8 to 5.5 V), LV (Low-voltage main) mode: 1 to 4 MHz (V _{DD} = 1.6 to 5.5 V)	
Clock for 16-bit timer KB20		48 MHz (TYP.): V _{DD} = 2.7 to 5.5 V	
Subsystem clock		XT1 (crystal) oscillation, external subsystem clock input (EXCLKS) 32.768 kHz (TYP.): V _{DD} = 1.6 to 5.5 V	
Low-speed on-chip oscillator		15 kHz (TYP.)	
General-purpose register		(8-bit register × 8) × 4 banks	
Minimum instruction execution time		0.04167 μs (High-speed on-chip oscillator: f _H = 24 MHz operation)	
		0.05 μs (High-speed system clock: f _{MX} = 20 MHz operation)	
		30.5 μs (Subsystem clock: f _{SUB} = 32.768 kHz operation)	
Instruction set		<ul style="list-style-type: none"> • Data transfer (8/16 bits) • Adder and subtractor/logical operation (8/16 bits) • Multiplication (8 bits × 8 bits) • Rotate, barrel shift, and bit manipulation (Set, reset, test, and Boolean operation), etc. 	
I/O port	Total	49	65
	CMOS I/O	42 (N-ch O.D. I/O [V _{DD} withstand voltage]: 12)	58 (N-ch O.D. I/O [V _{DD} withstand voltage]: 18)
	CMOS input	5	5
	CMOS output	–	–
	N-ch O.D I/O (withstand voltage: 6 V)	2	2
Timer	16-bit timer TAU	8 channels	
	16-bit timer KB20	1 channel	
	Watchdog timer	1 channel	
	12-bit interval timer (IT)	1 channel	
	Real-time clock 2	1 channel	
	RTC2 output	1 • 1 Hz (subsystem clock: f _{SUB} = 32.768 kHz)	
	Timer output	8 channels (PWM outputs: 7 ^{Note 2}) (TAU used) 1 channel (timer KB20 used)	
	Remote control output function	1 (TAU used)	

Notes 1. In the case of the 8 KB, this is about 7 KB when the self-programming function and data flash function are used.

2. The number of outputs varies depending on the setting of the channels in use and the number of master channels (see **6.9.3 Operation as multiple PWM output function** in the RL78/L13 User's Manual.).

(2/2)

Item	64-pin		80-pin	
	R5F10WLx (x = A, C-G)		R5F10WMx (x = A, C-G)	
Clock output/buzzer output controller	2			
	<ul style="list-style-type: none"> • 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: $f_{MAIN} = 20$ MHz operation) • 256 Hz, 512 Hz, 1.024 kHz, 2.048 kHz, 4.096 kHz, 8.192 kHz, 16.384 kHz, 32.768 kHz (Subsystem clock: $f_{SUB} = 32.768$ kHz operation) 			
8/10-bit resolution A/D converter	9 channels		12 channels	
Comparator	2 channels			
Serial interface	[64-pin]			
	<ul style="list-style-type: none"> • CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I²C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I²C: 1 channel • UART: 1 channel 			
I ² C bus	[80-pin]			
	<ul style="list-style-type: none"> • CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I²C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I²C: 1 channel • UART: 2 channels 			
LCD controller/driver	Internal voltage boosting method, capacitor split method, and external resistance division method are switchable.			
Segment signal output	36 (32) ^{Note 1}		51 (47) ^{Note 1}	
Common signal output	4 (8) ^{Note 1}			
Multiplier and divider/multiply-accumulator	<ul style="list-style-type: none"> • 16 bits × 16 bits = 32 bits (Unsigned or signed) • 32 bits ÷ 32 bits = 32 bits (Unsigned) • 16 bits × 16 bits + 32 bits = 32 bits (Unsigned or signed) 			
DMA controller	4 channels			
Vectored interrupt sources	Internal	32		35
	External	11		11
Key interrupt	5		8	
Reset	<ul style="list-style-type: none"> • Reset by RESET pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution^{Note 2} • Internal reset by RAM parity error • Internal reset by illegal-memory access 			
Power-on-reset circuit	<ul style="list-style-type: none"> • Power-on-reset: 1.51 V (TYP.) • Power-down-reset: 1.50 V (TYP.) 			
Voltage detector	<ul style="list-style-type: none"> • Rising edge: 1.67 V to 4.06 V (14 steps) • Falling edge: 1.63 V to 3.98 V (14 steps) 			
On-chip debug function	Provided			
Power supply voltage	$V_{DD} = 1.6$ to 5.5 V (TA = -40 to +85°C) $V_{DD} = 2.4$ to 5.5 V (TA = -40 to +105°C)			
Operating ambient temperature	Consumer applications: TA = -40 to +85°C Industrial applications: TA = -40 to +105°C			

Notes 1. The values in parentheses are the number of signal outputs when 8 com is used.

2. This reset occurs when instruction code FFH is executed.

This reset does not occur during emulation using an in-circuit emulator or an on-chip debugging emulator.

2. ELECTRICAL SPECIFICATIONS ($T_A = -40$ to $+85^\circ\text{C}$)

Target products A: Consumer applications; $T_A = -40$ to $+85^\circ\text{C}$

R5F10WLAAFA, R5F10WLCAFA, R5F10WLDAFA,
R5F10WLEAFA, R5F10WLFAFA, R5F10WLGafa,
R5F10WLAAFB, R5F10WLCAFB, R5F10WLDAFB,
R5F10WLEAFB, R5F10WLFAFB, R5F10WLGAFB,
R5F10WMAAFA, R5F10WMCAFA, R5F10WMDAFA,
R5F10WMEAFA, R5F10WMFAFA, R5F10WMGAFA,
R5F10WMAAFB, R5F10WMCAFB, R5F10WMDAFB,
R5F10WMEAFB, R5F10WMFAFB, R5F10WMGAFB

G: Industrial applications; when using $T_A = -40$ to $+105^\circ\text{C}$ specification products at $T_A = -40$ to $+85^\circ\text{C}$

R5F10WLAGFB, R5F10WLCGFB, R5F10WLDGFB,
R5F10WLEGFB, R5F10WLFGFB, R5F10WLGgfb,
R5F10WMAGFB, R5F10WMCgfb, R5F10WMDGFB,
R5F10WMEGFB, R5F10WMFGFB, R5F10WMGgfb

- Cautions**
1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
 2. The pins mounted depend on the product. See 2.1 Port Function to 2.2.1 With functions for each product in the RL78/L13 User's Manual.

2.1 Absolute Maximum Ratings

Absolute Maximum Ratings (1/3)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V _{DD}		-0.5 to +6.5	V
REGC pin input voltage	V _{I_{REGC}}	REGC	-0.3 to +2.8 and -0.3 to V _{DD} +0.3 ^{Note 1}	V
Input voltage	V _{I1}	P00 to P07, P10 to P17, P20 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P121 to P127, P130, P137	-0.3 to V _{DD} +0.3 ^{Note 2}	V
	V _{I2}	P60 and P61 (N-ch open-drain)	-0.3 to +6.5	V
	V _{I3}	EXCLK, EXCLKS, RESET [¯]	-0.3 to V _{DD} +0.3 ^{Note 2}	V
Output voltage	V _{O1}	P00 to P07, P10 to P17, P20 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P121 to P127, P130, P137	-0.3 to V _{DD} +0.3 ^{Note 2}	V
Analog input voltage	V _{AI1}	ANI0, ANI1, ANI16 to ANI26	-0.3 to V _{DD} +0.3 and -0.3 to AV _{REF(+)} +0.3 ^{Notes 2, 3}	V

Notes 1. Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μF). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.

2. Must be 6.5 V or lower.

3. Do not exceed AV_{REF(+)} + 0.3 V in case of A/D conversion target pin.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remarks 1. Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2. AV_{REF(+)}: + side reference voltage of the A/D converter.

3. V_{SS}: Reference voltage

Absolute Maximum Ratings (2/3)

Parameter	Symbol	Conditions	Ratings	Unit
LCD voltage	V _{L1}	V _{L1} voltage ^{Note 1}	-0.3 to +2.8 and -0.3 to V _{L4} +0.3	V
	V _{L2}	V _{L2} voltage ^{Note 1}	-0.3 to V _{L4} +0.3 ^{Note 2}	V
	V _{L3}	V _{L3} voltage ^{Note 1}	-0.3 to V _{L4} +0.3 ^{Note 2}	V
	V _{L4}	V _{L4} voltage ^{Note 1}	-0.3 to +6.5	V
	V _{LCAP}	CAPL, CAPH voltage ^{Note 1}	-0.3 to V _{L4} +0.3 ^{Note 2}	V
	V _{OUT}	COM0 to COM7 SEG0 to SEG50 output voltage	External resistance division method	-0.3 to V _{DD} +0.3 ^{Note 2}
		Capacitor split method	-0.3 to V _{DD} +0.3 ^{Note 2}	V
		Internal voltage boosting method	-0.3 to V _{L4} +0.3 ^{Note 2}	V

Notes 1. This value only indicates the absolute maximum ratings when applying voltage to the V_{L1}, V_{L2}, V_{L3}, and V_{L4} pins; it does not mean that applying voltage to these pins is recommended. When using the internal voltage boosting method or capacitance split method, connect these pins to V_{SS} via a capacitor (0.47 μF ± 30%) and connect a capacitor (0.47 μF ± 30%) between the CAPL and CAPH pins.

2. Must be 6.5 V or lower.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark V_{SS}: Reference voltage

Absolute Maximum Ratings (3/3)

Parameter	Symbol	Conditions		Ratings	Unit
<R> Output current, high	I _{OH1}	Per pin	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P125 to P127, P130	-40	mA
<R>		Total of all pins -170 mA	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P125 to P127, P130	-170	mA
<R>	I _{OH2}	Per pin	P20, P21	-0.5	mA
<R>		Total of all pins		-1	mA
<R> Output current, low	I _{OL1}	Per pin	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P125 to P127, P130	40	mA
<R>		Total of all pins 170 mA	P40 to P47, P130	70	mA
<R>			P00 to P07, P10 to P17, P22 to P27, P30 to P35, P50 to P57, P60, P61, P70 to P77, P125 to P127	100	mA
<R>	I _{OL2}	Per pin	P20, P21	1	mA
<R>		Total of all pins		2	mA
Operating ambient temperature	T _A	In normal operation mode		-40 to +85	°C
		In flash memory programming mode			
Storage temperature	T _{stg}			-65 to +150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2.2 Oscillator Characteristics

2.2.1 X1 and XT1 oscillator characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation frequency (f_x) ^{Note}	Ceramic resonator/ crystal resonator	$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	1.0		20.0	MHz
		$2.4\text{ V} \leq V_{DD} < 2.7\text{ V}$	1.0		16.0	
		$1.8\text{ V} \leq V_{DD} < 2.4\text{ V}$	1.0		8.0	
		$1.6\text{ V} \leq V_{DD} < 1.8\text{ V}$	1.0		4.0	
XT1 clock oscillation frequency (f_{XT}) ^{Note}	Crystal resonator		32	32.768	35	kHz

Note Indicates only permissible oscillator frequency ranges. Refer to **AC Characteristics** for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

Caution Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

Remark When using the X1 oscillator and XT1 oscillator, see 5.4 System Clock Oscillator in the RL78/L13 User's Manual.

2.2.2 On-chip oscillator characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequency ^{Notes 1, 2}	f_{IH}			1		24	MHz
High-speed on-chip oscillator clock frequency accuracy		-20 to $+85^\circ\text{C}$	$1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	-1.0		+1.0	%
			$1.6\text{ V} \leq V_{DD} < 1.8\text{ V}$	-5.0		+5.0	%
		-40 to -20°C	$1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	-1.5		+1.5	%
			$1.6\text{ V} \leq V_{DD} < 1.8\text{ V}$	-5.5		+5.5	%
Low-speed on-chip oscillator clock frequency	f_{IL}				15		kHz
Low-speed on-chip oscillator clock frequency accuracy				-15		+15	%

Notes 1. The high-speed on-chip oscillator frequency is selected by bits 0 to 4 of the option byte (000C2H/010C2H) and bits 0 to 2 of the HOCODIV register.

2. This indicates the oscillator characteristics only. Refer to **AC Characteristics** for the instruction execution time.

2.3 DC Characteristics

2.3.1 Pin characteristics

(T_A = -40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Output current, high ^{Note 1}	I _{OH1}	Per pin for P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130	1.6 V ≤ V _{DD} ≤ 5.5 V			-10.0 ^{Note 2}	mA
		Total of P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130 (When duty = 70% ^{Note 3})	4.0 V ≤ V _{DD} ≤ 5.5 V			-90.0	mA
			2.7 V ≤ V _{DD} < 4.0 V			-15.0	mA
			1.8 V ≤ V _{DD} < 2.7 V			-7.0	mA
	I _{OH2}	Per pin for P20 and P21	1.6 V ≤ V _{DD} ≤ 5.5 V			-0.1 ^{Note 2}	mA
		Total of all pins (When duty = 70% ^{Note 3})	1.6 V ≤ V _{DD} ≤ 5.5 V			-0.2	mA

<R>

Notes 1. Value of the current at which the device operation is guaranteed even if the current flows from the V_{DD} pin to an output pin

2. Do not exceed the total current value.

3. Output current value under conditions where the duty factor ≤ 70%.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

- Total output current of pins = (I_{OH} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OH} = -90.0 mA

$$\text{Total output current of pins} = (-90.0 \times 0.7)/(80 \times 0.01) \cong -78.75 \text{ mA}$$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Caution P00, P04 to P07, P16, P17, P35, P42 to P44, P46, P47, P53 to P56, and P130 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = -40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Output current, I _{OL} ^{Note 1}	I _{OL1}	Per pin for P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130			20.0 ^{Note 2}	mA	
		Per pin for P60 and P61			15.0 ^{Note 2}	mA	
		Total of P40 to P47, P130 (When duty = 70% ^{Note 3})	4.0 V ≤ V _{DD} ≤ 5.5 V			70.0	mA
			2.7 V ≤ V _{DD} < 4.0 V			15.0	mA
			1.8 V ≤ V _{DD} < 2.7 V			9.0	mA
			1.6 V ≤ V _{DD} < 1.8 V			4.5	mA
		Total of P00 to P07, P10 to P17, P22 to P27, P30 to P35, P50 to P57, P70 to P77, P125 to P127 (When duty = 70% ^{Note 3})	4.0 V ≤ V _{DD} ≤ 5.5 V			90.0	mA
			2.7 V ≤ V _{DD} < 4.0 V			35.0	mA
			1.8 V ≤ V _{DD} < 2.7 V			20.0	mA
			1.6 V ≤ V _{DD} < 1.8 V			10.0	mA
	Total of all pins (When duty = 70% ^{Note 3})					160.0	mA
	I _{OL2}	Per pin for P20 and P21				0.4 ^{Note 2}	mA
Total of all pins (When duty = 70% ^{Note 3})		1.6 V ≤ V _{DD} ≤ 5.5 V			0.8	mA	

<R>

- Notes**
- Value of the current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin
 - Do not exceed the total current value.
 - Output current value under conditions where the duty factor ≤ 70%.
 The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).
 - Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)
 <Example> Where n = 80% and I_{OL} = 70.0 mA
 Total output current of pins = (70.0 × 0.7)/(80 × 0.01) ≅ 61.25 mA
 However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = -40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input voltage, high	V _{IH1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130, P137	Normal input buffer	0.8V _{DD}		V _{DD}	V
	V _{IH2}	P03, P05, P06, P16, P17, P34, P43, P44, P46, P47, P53, P55	TTL input buffer 4.0 V ≤ V _{DD} ≤ 5.5 V	2.2		V _{DD}	V
			TTL input buffer 3.3 V ≤ V _{DD} < 4.0 V	2.0		V _{DD}	V
			TTL input buffer 1.6 V ≤ V _{DD} < 3.3 V	1.5		V _{DD}	V
	V _{IH3}	P20, P21		0.7V _{DD}		V _{DD}	V
	V _{IH4}	P60, P61		0.7V _{DD}		6.0	V
	V _{IH5}	P121 to P124, P137, EXCLK, EXCLKS, RESET		0.8V _{DD}		V _{DD}	V
Input voltage, low	V _{IL1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130, P137	Normal input buffer	0		0.2V _{DD}	V
	V _{IL2}	P03, P05, P06, P16, P17, P34, P43, P44, P46, P47, P53, P55	TTL input buffer 4.0 V ≤ V _{DD} ≤ 5.5 V	0		0.8	V
			TTL input buffer 3.3 V ≤ V _{DD} < 4.0 V	0		0.5	V
			TTL input buffer 1.6 V ≤ V _{DD} < 3.3 V	0		0.32	V
	V _{IL3}	P20, P21		0		0.3V _{DD}	V
	V _{IL4}	P60, P61		0		0.3V _{DD}	V
	V _{IL5}	P121 to P124, P137, EXCLK, EXCLKS, RESET		0		0.2V _{DD}	V

Caution The maximum value of V_{IH} of pins P00, P04 to P07, P16, P17, P35, P42 to P44, P46, P47, P53 to P56, and P130 is V_{DD}, even in the N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = -40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit		
Output voltage, high	V _{OH1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130	4.0 V ≤ V _{DD} ≤ 5.5 V, I _{OH1} = -10.0 mA	V _{DD} - 1.5			V	
			4.0 V ≤ V _{DD} ≤ 5.5 V, I _{OH1} = -3.0 mA	V _{DD} - 0.7			V	
			2.7 V ≤ V _{DD} ≤ 5.5 V, I _{OH1} = -2.0 mA	V _{DD} - 0.6			V	
			1.8 V ≤ V _{DD} ≤ 5.5 V, I _{OH1} = -1.5 mA	V _{DD} - 0.5			V	
			1.6 V ≤ V _{DD} ≤ 5.5 V, I _{OH1} = -1.0 mA	V _{DD} - 0.5			V	
	V _{OH2}	P20 and P21	1.6 V ≤ V _{DD} ≤ 5.5 V, I _{OH2} = -100 μA	V _{DD} - 0.5			V	
Output voltage, low	V _{OL1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130	4.0 V ≤ V _{DD} ≤ 5.5 V, I _{OL1} = 20 mA			1.3	V	
			4.0 V ≤ V _{DD} ≤ 5.5 V, I _{OL1} = 8.5 mA			0.7	V	
			2.7 V ≤ V _{DD} ≤ 5.5 V, I _{OL1} = 3.0 mA			0.6	V	
			2.7 V ≤ V _{DD} ≤ 5.5 V, I _{OL1} = 1.5 mA			0.4	V	
			1.8 V ≤ V _{DD} ≤ 5.5 V, I _{OL1} = 0.6 mA			0.4	V	
			1.6 V ≤ V _{DD} < 1.8 V, I _{OL1} = 0.3 mA			0.4	V	
		V _{OL2}	P20 and P21	1.6 V ≤ V _{DD} ≤ 5.5 V, I _{OL2} = 400 μA			0.4	V
	V _{OL3}	P60 and P61	4.0 V ≤ V _{DD} ≤ 5.5 V, I _{OL3} = 15.0 mA			2.0	V	
			4.0 V ≤ V _{DD} ≤ 5.5 V, I _{OL3} = 5.0 mA			0.4	V	
			2.7 V ≤ V _{DD} ≤ 5.5 V, I _{OL3} = 3.0 mA			0.4	V	
			1.8 V ≤ V _{DD} ≤ 5.5 V, I _{OL3} = 2.0 mA			0.4	V	
1.6 V ≤ V _{DD} < 1.8 V, I _{OL3} = 1.0 mA					0.4	V		

Caution P00, P04 to P07, P16, P17, P35, P42 to P44, P46, P47, P53 to P56, and P130 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

($T_A = -40$ to $+85^\circ\text{C}$, $1.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit		
Input leakage current, high	I_{LH1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130, P137	$V_I = V_{DD}$			1	μA	
	I_{LH2}	P20 and P21, $\overline{\text{RESET}}$	$V_I = V_{DD}$			1	μA	
	I_{LH3}	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)	$V_I = V_{DD}$	In input port mode and when external clock is input			1	μA
				Resonator connected			10	μA
Input leakage current, low	I_{LIL1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130, P137	$V_I = V_{SS}$			-1	μA	
	I_{LIL2}	P20 and P21, $\overline{\text{RESET}}$	$V_I = V_{SS}$			-1	μA	
	I_{LIL3}	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)	$V_I = V_{SS}$	In input port mode and when external clock is input			-1	μA
				Resonator connected			-10	μA
On-chip pull-up resistance	R_{U1}	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P45 to P47, P50 to P57, P70 to P77, P125 to P127, P130	$V_I = V_{SS}$	$2.4\text{ V} \leq V_{DD} < 5.5\text{ V}$	10	20	100	$\text{k}\Omega$
				$1.6\text{ V} \leq V_{DD} < 2.4\text{ V}$	10	30	100	$\text{k}\Omega$
	R_{U2}	P40 to P44	$V_I = V_{SS}$		10	20	100	$\text{k}\Omega$

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2.3.2 Supply current characteristics

(T_A = -40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

(1/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit	
Supply current ^{Note 1}	I _{DD1}	Operating mode	HS (high-speed main) mode ^{Note 5}	f _{HOCO} = 48 MHz ^{Note 3} , f _{IH} = 24 MHz ^{Note 3}	Basic operation	V _{DD} = 5.0 V		2.0		mA
						V _{DD} = 3.0 V		2.0		mA
				Normal operation	V _{DD} = 5.0 V		3.8	6.5	mA	
					V _{DD} = 3.0 V		3.8	6.5	mA	
				Basic operation	V _{DD} = 5.0 V		1.7		mA	
					V _{DD} = 3.0 V		1.7		mA	
			Normal operation	V _{DD} = 5.0 V		3.6	6.1	mA		
				V _{DD} = 3.0 V		3.6	6.1	mA		
			Normal operation	V _{DD} = 5.0 V		2.7	4.7	mA		
				V _{DD} = 3.0 V		2.7	4.7	mA		
			LS (low-speed main) mode ^{Note 5}	f _{HOCO} = 8 MHz ^{Note 3} , f _{IH} = 8 MHz ^{Note 3}	Normal operation	V _{DD} = 3.0 V		1.2	2.1	mA
						V _{DD} = 2.0 V		1.2	2.1	mA
			LV (low-voltage main) mode ^{Note 5}	f _{HOCO} = 4 MHz ^{Note 3} , f _{IH} = 4 MHz ^{Note 3}	Normal operation	V _{DD} = 3.0 V		1.2	1.8	mA
						V _{DD} = 2.0 V		1.2	1.8	mA
			HS (high-speed main) mode ^{Note 5}	f _{MX} = 20 MHz ^{Note 2} , V _{DD} = 5.0 V	Normal operation	Square wave input		3.0	5.1	mA
						Resonator connection		3.2	5.2	mA
				f _{MX} = 20 MHz ^{Note 2} , V _{DD} = 3.0 V	Normal operation	Square wave input		2.9	5.1	mA
						Resonator connection		3.2	5.2	mA
				f _{MX} = 16 MHz ^{Note 2} , V _{DD} = 5.0 V	Normal operation	Square wave input		2.5	4.4	mA
						Resonator connection		2.7	4.5	mA
				f _{MX} = 16 MHz ^{Note 2} , V _{DD} = 3.0 V	Normal operation	Square wave input		2.5	4.4	mA
						Resonator connection		2.7	4.5	mA
				f _{MX} = 10 MHz ^{Note 2} , V _{DD} = 5.0 V	Normal operation	Square wave input		1.9	3.0	mA
						Resonator connection		1.9	3.0	mA
				f _{MX} = 10 MHz ^{Note 2} , V _{DD} = 3.0 V	Normal operation	Square wave input		1.9	3.0	mA
						Resonator connection		1.9	3.0	mA
			LS (low-speed main) mode ^{Note 5}	f _{MX} = 8 MHz ^{Note 2} , V _{DD} = 3.0 V	Normal operation	Square wave input		1.1	2.0	mA
						Resonator connection		1.1	2.0	mA
				f _{MX} = 8 MHz ^{Note 2} , V _{DD} = 2.0 V	Normal operation	Square wave input		1.1	2.0	mA
						Resonator connection		1.1	2.0	mA
Subsystem clock operation	f _{SUB} = 32.768 kHz ^{Note 4} , T _A = -40°C	Normal operation	Square wave input		4.0	5.4	μA			
			Resonator connection		4.3	5.4	μA			
	f _{SUB} = 32.768 kHz ^{Note 4} , T _A = +25°C	Normal operation	Square wave input		4.0	5.4	μA			
			Resonator connection		4.3	5.4	μA			
	f _{SUB} = 32.768 kHz ^{Note 4} , T _A = +50°C	Normal operation	Square wave input		4.1	7.1	μA			
			Resonator connection		4.4	7.1	μA			
	f _{SUB} = 32.768 kHz ^{Note 4} , T _A = +70°C	Normal operation	Square wave input		4.3	8.7	μA			
			Resonator connection		4.7	8.7	μA			
f _{SUB} = 32.768 kHz ^{Note 4} , T _A = +85°C	Normal operation	Square wave input		4.7	12.0	μA				
		Resonator connection		5.2	12.0	μA				

(Notes and Remarks are listed on the next page.)

- Notes**
1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.
 2. When high-speed on-chip oscillator and subsystem clock are stopped.
 3. When high-speed system clock and subsystem clock are stopped.
 4. When high-speed on-chip oscillator and high-speed system clock are stopped. When setting ultra-low power consumption oscillation (AMPHS1 = 1). The current flowing into the LCD controller/driver, 16-bit timer KB20, real-time clock 2, 12-bit interval timer, and watchdog timer is not included.
 5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
 - HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz
2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
 - LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz
 - LV (low-voltage main) mode: 1.6 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 4 MHz

- Remarks**
1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
 2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)
 3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)
 4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)
 5. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

(T_A = -40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

(2/2)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit	
Supply current ^{Note 1}	I _{DD2} ^{Note 2}	HALT mode	HS (high-speed main) mode ^{Note 7}	f _{HOCO} = 48 MHz ^{Note 4} , f _{IH} = 24 MHz ^{Note 4}	V _{DD} = 5.0 V	0.71	1.95	mA	
					V _{DD} = 3.0 V	0.71	1.95		
				f _{HOCO} = 24 MHz ^{Note 4} , f _{IH} = 24 MHz ^{Note 4}	V _{DD} = 5.0 V	0.49	1.64	mA	
					V _{DD} = 3.0 V	0.49	1.64		
				f _{HOCO} = 16 MHz ^{Note 4} , f _{IH} = 16 MHz ^{Note 4}	V _{DD} = 5.0 V	0.43	1.11	mA	
					V _{DD} = 3.0 V	0.43	1.11		
			LS (low-speed main) mode ^{Note 7}	f _{HOCO} = 8 MHz ^{Note 4} , f _{IH} = 8 MHz ^{Note 4}	V _{DD} = 3.0 V	280	770	μA	
				V _{DD} = 2.0 V	280	770			
			LV (low-voltage main) mode ^{Note 7}	f _{HOCO} = 4 MHz ^{Note 4} , f _{IH} = 4 MHz ^{Note 4}	V _{DD} = 3.0 V	430	700	μA	
					V _{DD} = 2.0 V	430	700		
			HS (high-speed main) mode ^{Note 7}	f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input	0.31	1.42	mA	
					Resonator connection	0.48	1.42		
					f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input	0.29	1.42	mA
						Resonator connection	0.48	1.42	
					f _{MX} = 16 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input	0.26	0.86	mA
						Resonator connection	0.45	1.15	
				f _{MX} = 16 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input	0.25	0.86	mA	
					Resonator connection	0.44	1.15		
	f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input		0.20	0.63	mA			
		Resonator connection		0.28	0.71				
	f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		0.19	0.63	mA			
		Resonator connection		0.28	0.71				
	LS (low-speed main) mode ^{Note 7}	f _{MX} = 8 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input	100	560	μA			
			Resonator connection	160	560				
f _{MX} = 8 MHz ^{Note 3} , V _{DD} = 2.0 V		Square wave input	100	560	μA				
		Resonator connection	160	560					
Subsystem clock operation	f _{SUB} = 32.768 kHz ^{Note 5} , T _A = -40°C	Square wave input	0.34	0.62	μA				
		Resonator connection	0.51	0.80					
	f _{SUB} = 32.768 kHz ^{Note 5} , T _A = +25°C	Square wave input	0.38	0.62	μA				
		Resonator connection	0.57	0.80					
	f _{SUB} = 32.768 kHz ^{Note 5} , T _A = +50°C	Square wave input	0.46	2.30	μA				
		Resonator connection	0.67	2.49					
	f _{SUB} = 32.768 kHz ^{Note 5} , T _A = +70°C	Square wave input	0.65	4.03	μA				
		Resonator connection	0.91	4.22					
	f _{SUB} = 32.768 kHz ^{Note 5} , T _A = +85°C	Square wave input	1.00	8.04	μA				
		Resonator connection	1.31	8.23					
I _{DD3} ^{Note 6}	STOP mode ^{Note 8}	T _A = -40°C	0.18	0.52	μA				
		T _A = +25°C	0.24	0.52					
		T _A = +50°C	0.33	2.21					
		T _A = +70°C	0.53	3.94					
		T _A = +85°C	0.93	7.95					

(Notes and Remarks are listed on the next page.)

- Notes**
1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.
 2. During HALT instruction execution by flash memory.
 3. When high-speed on-chip oscillator and subsystem clock are stopped.
 4. When high-speed system clock and subsystem clock are stopped.
 5. When high-speed on-chip oscillator and high-speed system clock are stopped.
When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1). The current flowing into the real-time clock 2 is included. However, not including the current flowing into the clock output/buzzer output, 12-bit interval timer, and watchdog timer.
 6. Not including the current flowing into the real-time clock 2, clock output/buzzer output, 12-bit interval timer, and watchdog timer.
 7. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
 HS (high-speed main) mode: $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}@1\text{ MHz to }24\text{ MHz}$
 $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}@1\text{ MHz to }16\text{ MHz}$
 LS (low-speed main) mode: $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}@1\text{ MHz to }8\text{ MHz}$
 LV (low-voltage main) mode: $1.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}@1\text{ MHz to }4\text{ MHz}$
 8. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.

- Remarks**
1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
 2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)
 3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)
 4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)
 5. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is T_A = 25°C